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Appln. No. 10/049,170 Amendment Dated November 20, 2003 Reply to Office Action of September 2, 2003

<u>Amendments t the Claims:</u> This listing of claims will replace all prior versions, and listings, of claims in the application

Listing of Claims:

1. (Currently Amended) A method for manufacturing a ceramic substrate, comprising the steps of:

forming a conductive pattern through filling an intaglio with a conductive paste;

forming an adhesive layer on a heat-resistant substrate;

heat-pressing the intaglio onto the adhesive layer;

removing the intaglio; and

forming a first assembly through stackstacking an un-sintered green sheet to cover the conductive pattern and through heat-pressing the un-sintered green sheet.

- 2. (Original) The method of claim 1, further comprising the step of performing a binder-removing process and a sintering process to the first assembly.
- 3. (Previously Presented) The method of claim 1, further comprising the steps of:

forming a via-conductor through forming a through-hole in the un-sintered green sheet; and

connecting the conductive pattern to the via conductor.

4. (Original) The method of claim 1, further comprising the steps of:

forming a plurality of the first assemblies through repeating said steps of forming the conductive pattern, forming the adhesive layer; heat-pressing the intaglio, removing the intaglio, and forming the first assembly; and

forming a second assembly through stacking the first assemblies.

5. (Original) The method of claim 4, further comprising the step of performing a binder-removing process and a sintering process to the second assembly.

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removing the intaglio; and

- 6. (Previously Presented) The method of claim 4, further comprising the steps of:
- forming a via-conductor through forming a through-hole in the un-sintered green sheet; and
 - connecting the conductive pattern to the via-conductor.
- 7. (Original) A method for manufacturing a ceramic substrate, comprising the steps of: forming a conductive pattern through filling an intaglio with a conductive paste; forming an adhesive layer on a sintered ceramic substrate; heat-pressing the intaglio onto the adhesive layer;

forming a first assembly through stacking an un-sintered green sheet to cover the conductive pattern and through heat-pressing the un-sintered green sheet.

- 8. (Original) The method of claim 7, further comprising the step of performing a binder-removing process and a burning process to the first assembly.
- 9. (Previously Presented) The method of claim 7, further comprising the steps of:

forming a via-conductor through forming a through-hole in the un-sintered green sheet; and

- connecting the conductive patterns to the via-conductor.
- 10. (Previously Presented) The method of claim 7, further comprising the steps of: forming a via-conductor through forming a through-hole in the sintered substrate; and
 - connecting the conductive pattern to the via-conductor.
- 11. (Original) The method of claim 7, further comprising the steps of:

forming a plurality of the first assemblies through repeating the steps of forming the conductive pattern, forming the adhesive layer, heat-pressing the intaglio, removing the intaglio, and forming the first assembly; and

forming a second assembly through stacking the first assemblies and an un-sintered ceramic green sheet alternatively.

- 12. (Original) The method of claim 11, further comprising the step of performing a binder-removing process and a sintering process to the second assembly.
- 13. (Previously Presented) The method of claim 11, further comprising the step of:

forming a via-conductor through forming a through-hole in the un-sintered green sheet; and

connecting the conductive patterns to the via-hole conductor.

14. (Previously Presented) The method of claim 11, further comprising the steps of:

forming a via-conductor through forming a through-hole in the sintered ceramic substrate; and

connecting the conductive pattern to the via-conductor.

15. (Original) A method for manufacturing a ceramic substrate, comprising the steps of:

forming a first conductive pattern through filling a first intaglio with a conductive paste;

forming a first adhesive layer on a first heat-resistant substrate;

heat-pressing the first intaglio onto the first adhesive layer;

removing the first intaglio;

forming a first assembly through stacking an un-sintered green sheet to cover the first conductive pattern and heat-pressing the un-sintered green sheet;

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forming a second conductive pattern through filling a second intaglio with a conductive paste;

forming a second adhesive layer on a sintered ceramic substrate;

heat-pressing the second intaglio to the second adhesive layer;

removing the second intaglio; and

forming a second assembly through stacking the first assembly to cover the second conductive pattern and heat-pressing the first assembly.

- 16. (Original) The method of claim 15, further comprising the step of performing a binder-removing process and a sintering process to the second assembly.
- 17. (Previously Presented) The method of claim 15, wherein the first intaglio and the second intaglio are identical to each other.
- 18. (Previously Presented) The method of claim 15, further comprising the steps of:

forming a first via-conductor through forming a through-hole in the un-sintered green sheet; and

connecting at least one of the first and second conductive patterns to the first viaconductor.

19. (Previously Presented) The method of claim 15, further comprising the steps of:

forming a second via-conductor through forming a through-hole in the sintered ceramic substrate; and

connecting at least one of said first and second conductive patterns to the second via-conductor.

20. (New) The method of claim 1, further comprising the step of removing the first heat-resistant substrate from the conductor pattern.

21. (New) The method of claim 20, wherein said removing the first heat-resistant substrate comprises removing the first heat resistant substrate from the conductor pattern and the un-sintered green sheet.